

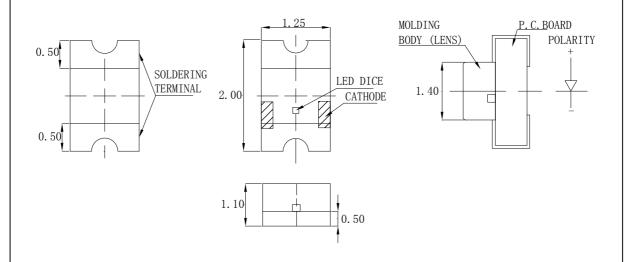
#### **Features**

- 2.0mm\*1.25mm SMT LED, Super thin (1.10H mm)
- Low Power Consumption
- Wide Viewing Angle
- Various Colors
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow and wave solder process.
- Meet ROHS Green Product.
- Package: 3000pcs/Reel

## **Applications**

· Backlight and Indicator

## **Package Dimensions**



## **Notes:**

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.2$ mm(.0079") unless otherwise noted.
- 3. Specifications are subject to change without notice
- 4. This drawing is only for reference, not as a basis for the actual structure.

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### FSL-20125110TB-TNCCL

### **Selection Guide**

Part No	Lens Type	Dice	Emitted Color
FSL-20125110TB-TNCCL	Water Clear	InGaN	Blue

# Electrical / Optical Characteristics At Ta=25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Iv	Luminous Intensity		112	288	mcd	IF=20mA
201/2	Viewing Angle		130		deg	IF=20mA
入 Peak	Peak Emission Wavelength		468		nm	IF=20mA
入 d	Dominant Wavelength	460	470	475	nm	IF=20mA
$\triangle \lambda$	Spectral Line Half-Width		25		nm	IF=20mA
VF	Forward Voltage		3.0		V	IF=20mA
IR	Reverse Current			10	μА	VR 5V

Note:

# **Absolute Maximum Ratings At Ta=25℃**

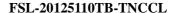
Parameter	Blue	Unit	
Power Dissipation	76	mW	
Peak Forward Current[1]	100	mA	
Continuous Forward Current	20	mA	
Derating Linear From 25℃	0.25	mA/℃	
Reverse Voltage	5	V	
Electrostatic Discharge Threshold (HBM)	150	V	
Operating Temperature Range	-20°C to + 80°C		
Storage Temperature Range	-30°C to + 100°C		
Soldering Condition	260°C For 5 Seconds		

Note:

1. 1/10DutyCycle, 0.1msPulseWidth

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 $<sup>1.\,\</sup>theta1/2$  is the angle from optical centerline where the luminous intensity is 1/2 optical centerline value





## Electrical Optical Characteristics Curves At Ta=25°C

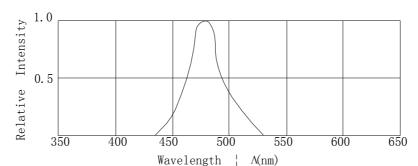
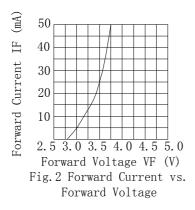
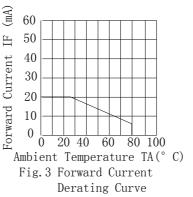
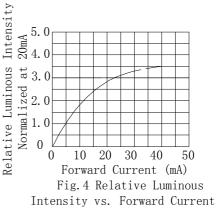


Fig. 1 Relative Intensity VS. Wavelength







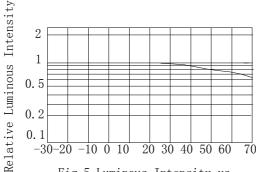


Fig. 5 Luminous Intensity vs. Ambient Temperature

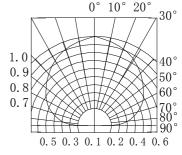


Fig. 6 Spatial Distribution

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# **Bin Range Of Luminous Intensity**

Symbol	Bin Code	Min.	Max.	Unit	Condition
	P	45	72	112	
T.,	Q	72	112		IF=20mA
Iv	R	112	180		
	S	180	288		

## **Bin Range Of Forward Voltage**

Symbol	Bin Code	Min.	Max.	Unit	Condition
	V0	2.6	2.8	V	IF=20mA
VF	V1	2.8	3.0		
	V2	3.0	3.2		
	V3	3.2	3.4		
	V4	3.4	3.6		
	V5	3.6	3.8		İ

# **Bin Range Of Dominate Wavelength**

Symbol	Bin Code	Min.	Max.	Unit	Condition
	В	460	465		
入 d	С	465	470	nm	IF=20mA
	D	470	475		

### Notes:

1. Tolerance of Luminous Intensity +/-20  $\!\%$ 

2. Tolerance of Forward Voltage +/-0.2V

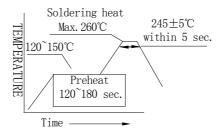
3. Tolerance of the Dominate Wavelength +/- 2nm

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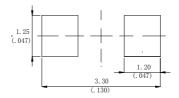
#### **SMT Reflow Soldering Instructions**



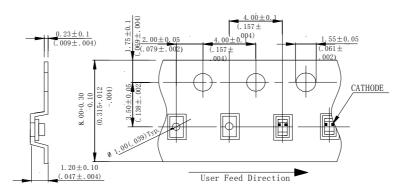
#### Notes:

- Sells gives no other assurances regarding the ability of to withstand ESD. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
- 2. Reflow soldering should not be done more than two times.
- 3. Do not stress LED when soldering, and do not warp the circuit board after soldering
- 4. While using Iron, Power dissipation of Iron should be smaller than 25W, and temperature should be controllable. The work should be finished within 2 sec under 320°C for once only.

### **Recommended Soldering Pad Dimensions**



#### Package Specifications (Units: mm (inches))



#### Notes:

- 1. The LEDs should be used within a year.
- 2. The LEDs should be kept in  $5\sim30^{\circ}$ C and 60% RH for less.
- 3. The LEDs should be used within 24 hours, or else should be kept a 5~30°C and 30% RH or less. And LEDs should be used within 7 days after opening the package.

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## **Reliability Test Items Conditions**

Classification	Test Item	Test Conditions	Test hours	Result
	Operation Life	Connect with a power IF=20mA Ta=Under room temperature	1000Hrs	0/20
F 1	High Temperature High Humidity	Ta=+65°C±5°C RH=90%-95%	240Hrs	0/20
Endurance Test	High Temperature Storage	High Ta=+85°C±5°C	1000Hrs	0/20
	Low Temperature Storage	Low Ta=-35°C±5°C Test time=1000hrs	1000Hrs	0/20
	Temperature Cycling	-45°C∼+105°C 15min 5min 15min	300 Cycles	0/20
Environmental	Thermal Shock	-35°C~±5°C~+85°C~±5°C 5min 10sec 5min	300 Cycles	0/20
Test Solder Resistance		Preheating: 120°C-150°C, within 2 minutes. Operation heating: 260°C (Max.), within 5 seconds (Max.)	5Cycles	0/20

# Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V <sub>F</sub> (V)	IF=20mA	Over U×1.2
Reverse current	Ir(µA)	V <sub>R</sub> =5V	Over U×2
Luminous intensity	Iv(mcd)	Ir=20mA	Below S×0.5

Note: 1.U means the upper limit of specified characteristics. S means initial value.

2.Meansurment shall be taken between 2 hours after the test pieces have been returned to normal ambient conditions after completion of each test.

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